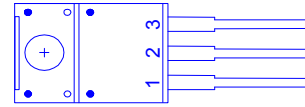
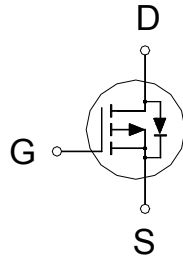


NIKO-SEM P-Channel Logic Level Enhancement Mode **P3506DTF**
 Field Effect Transistor **TO-220F**
 Halogen-Free & Lead-Free

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
-60V	35mΩ	-20A



1. GATE
2. DRAIN
3. SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	-60	V
Gate-Source Voltage		V_{GS}	±25	V
Continuous Drain Current	$T_C = 25\text{ }^\circ\text{C}$	I_D	-20	A
	$T_C = 100\text{ }^\circ\text{C}$		-10	
Pulsed Drain Current ¹		I_{DM}	-100	
Avalanche Current		I_{AS}	-38	
Avalanche Energy	$L = 0.1\text{mH}$	E_{AS}	72	mJ
Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$	P_D	26	W
	$T_C = 100\text{ }^\circ\text{C}$		10.4	
Junction & Storage Temperature Range		T_J, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		4.8	°C / W
Junction-to-Ambient	$R_{\theta JA}$		62.5	

¹Pulse width limited by maximum junction temperature.

ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	-60			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	-2	-2.7	-4	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 25V$			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -48V, V_{GS} = 0V$			1	μA
		$V_{DS} = -40V, V_{GS} = 0V, T_J = 55\text{ }^\circ\text{C}$			10	
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = -7V, I_D = -20A$		34	55	mΩ
		$V_{GS} = -10V, I_D = -20A$		29	35	
Forward Transconductance ¹	g_{fs}	$V_{DS} = -5V, I_D = -20A$		32		S

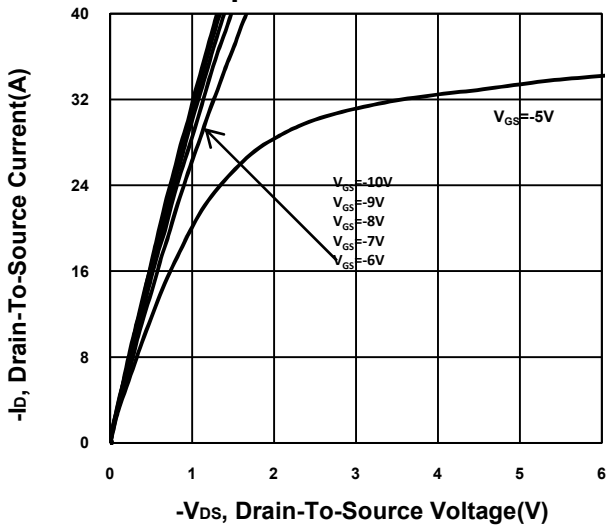
NIKO-SEM P-Channel Logic Level Enhancement Mode **P3506DTF**
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On-State Drain Current ¹	$I_{D(ON)}$	$V_{DS} = -5V, V_{GS} = -10V,$	-100			A
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = -25V, f = 1MHz$		2320		pF
Output Capacitance	C_{oss}			175		
Reverse Transfer Capacitance	C_{rss}			142		
Gate Resistance	R_g	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$		4.8		Ω
Total Gate Charge ²	Q_g	$V_{DS} = 0.5V_{(BR)DSS}, V_{GS} = -10V,$ $I_D = -20A$		43		nC
Gate-Source Charge ²	Q_{gs}			11		
Gate-Drain Charge ²	Q_{gd}			13.5		
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DS} = -30V,$ $I_D \cong -10A, V_{GS} = -10V, R_{GEN} = 25\Omega$		45		nS
Rise Time ²	t_r			380		
Turn-Off Delay Time ²	$t_{d(off)}$			70		
Fall Time ²	t_f			190		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ C$)						
Continuous Current	I_S				-20	A
Forward Voltage ¹	V_{SD}	$I_F = -20A, V_{GS} = 0V$			-1.3	V
Reverse Recovery Time	t_{rr}	$I_F = -20A, di_F/dt = 100A / \mu S$		40		nS
Reverse Recovery Charge	Q_{rr}				57	

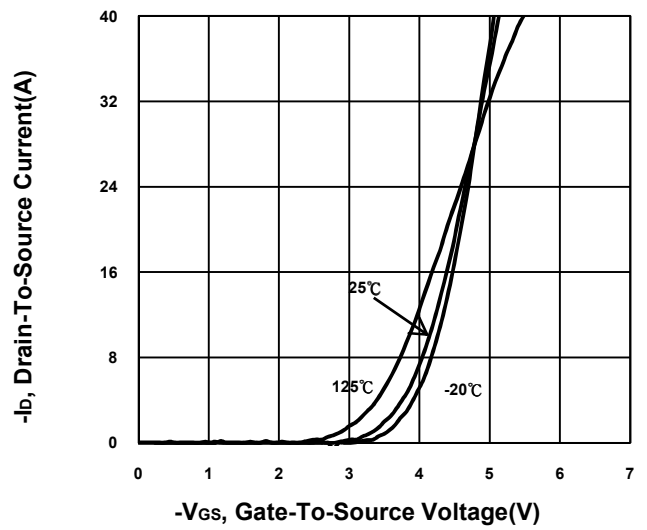
¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

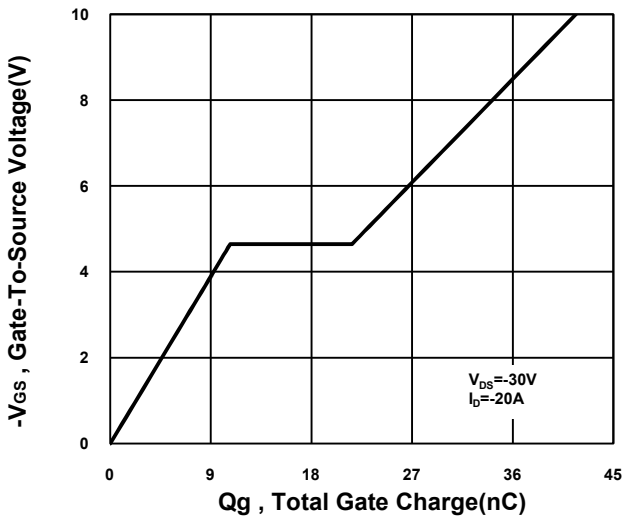
Output Characteristics



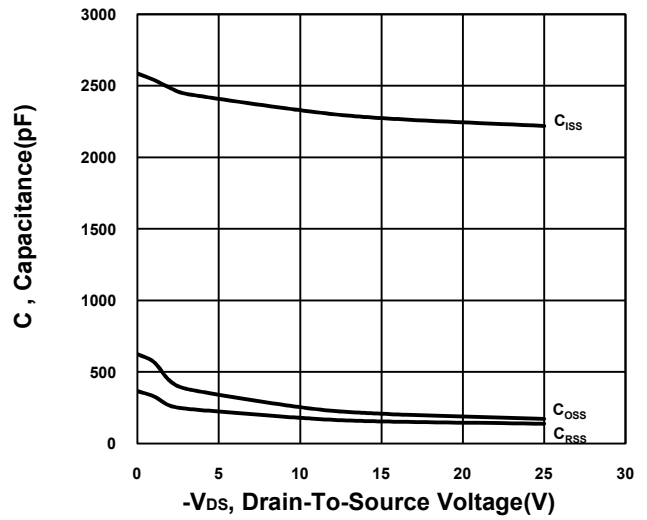
Transfer Characteristics



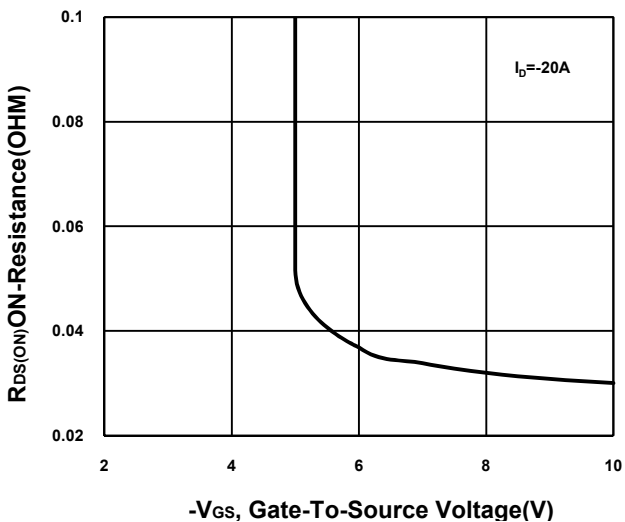
Gate charge Characteristics



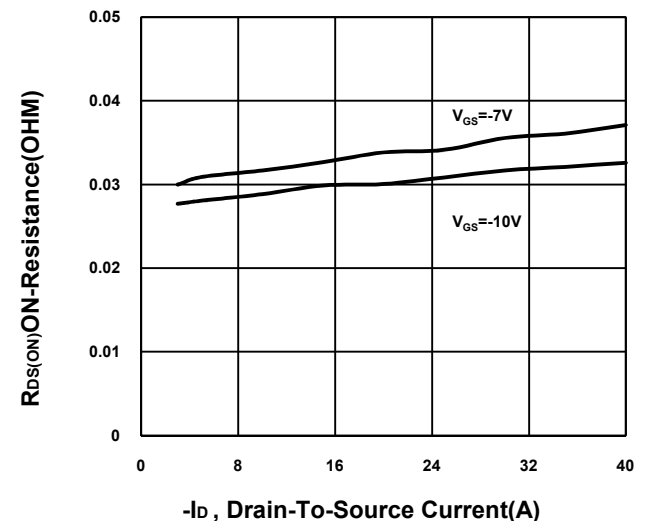
Capacitance Characteristic



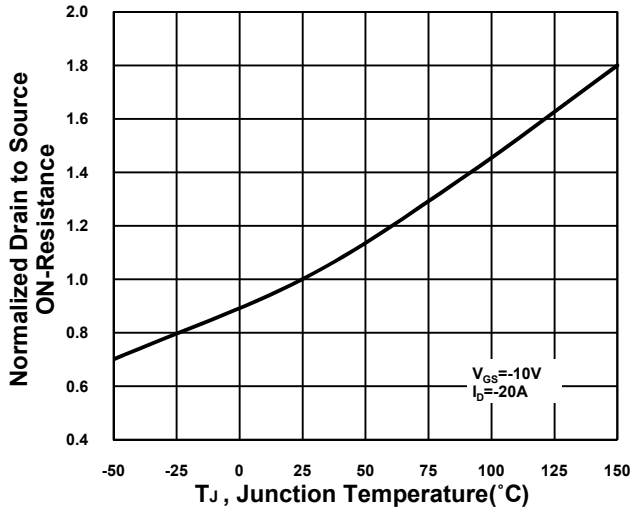
On-Resistance VS Gate-To-Source



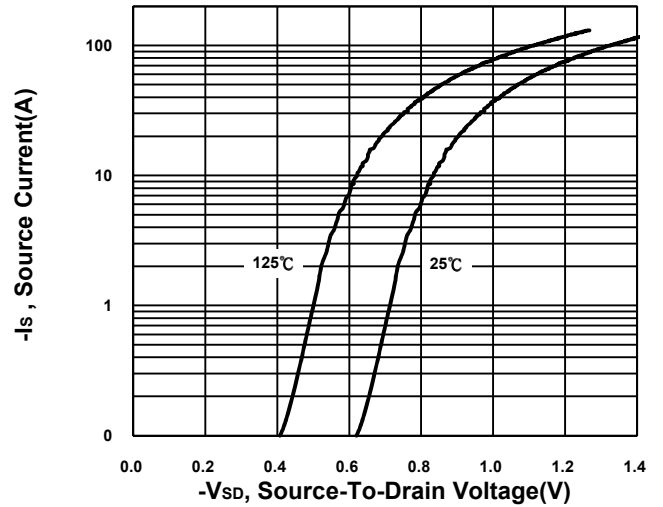
On-Resistance VS Drain Current



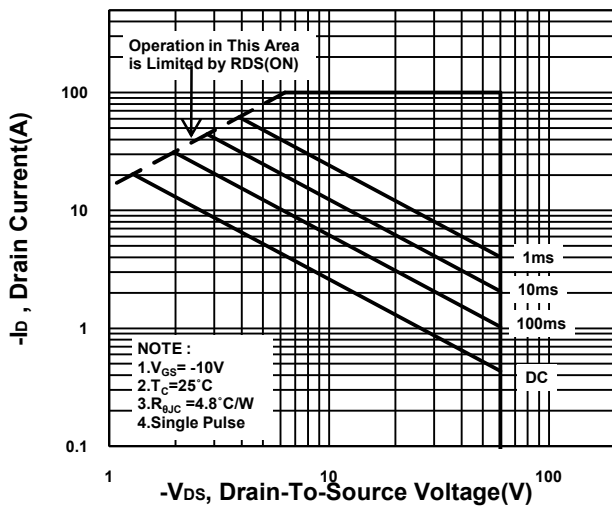
On-Resistance VS Temperature



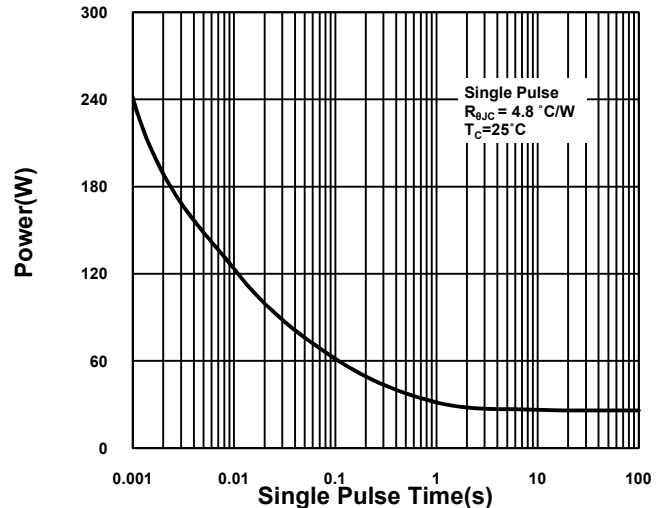
Source-Drain Diode Forward Voltage



Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

